

To investigate and model the key trade-offs, relevant to die attach adhesives for packaging/ CoB assembly of stress sensitive devices linked to the WP2 round-robin modelling activity

Objective

The overall programme will look at 3 stress sensitive structures

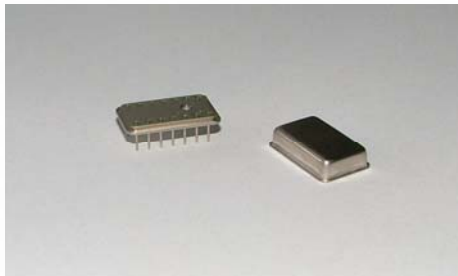
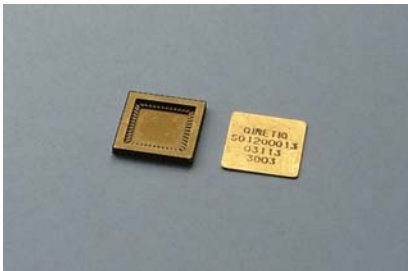
- Two Tyndall test structure arrays Fixed-fixed beams and cantilevers
- QinetiQ microphone

A number of different die attach adhesives will be used for the experimental work, with an appropriate range of CTE Modulus (stiffness) and thickness.

The round robin modelling will concentrate on a Kyocera 48 pin CLCC.

Additionally QinetiQ will consider a 14 pin DIL metal package and possibly PCB mounting of their microphone.

QinetiQ and Tyndall will perform comprehensive physical testing and modelling of their devices.



Partners involved

QinetiQ, Tyndall Institute, Fraunhofer IZM Berlin, Centre Spatial de Liege, University of Lancaster and partners in the linked WP2 round-robin modelling activity

Summary of results

New cross workpackages WP2 & WP4 project, started November 2005

Offer to industry

Benchmarked and validated models for MEMS packaging, including poorly matched assemblies

Contact

Alan Brown (agbrown@QinetiQ.com), Orla Slattery (orla.slattery@tyndall.ie)

Project status, date

New project started November 2005